

BENEQ TFS 200



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ALD research equipment that grows with you

- The most flexible ALD research platform ever designed for academic research and corporate R&D
- Superior quality coatings on wafers and planar objects
- Supports both thermal ALD and plasma-enhanced deposition (PEALD)
- Very fast processing times, cycle times even less than 2 second
- Options include in-situ diagnostics, load lock, FBR and many more...

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PROCESS TYPE

- thermal ALD
- plasma enhanced ALD
- face-up and face-down

USAGE

- R&D
- production

SUBSTRATE TYPE

- up to 200 mm wafer
- up to 200x200 mm
- 3D-parts
- powder

SUBSTRATE LOADING

- automatic
- manual

MAIN DIMENSIONS

- 1325x600x1298 mm

INTEGRATION

- glove box
- load-lock
- cluster

For product inquiries, please contact:

ald-sales@beneq.com

Technical information in this document is subject to change without notice. 3/2021

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